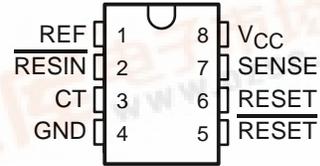


TL7702A, TL7705A, TL7709A, TL7712A, TL7715A SUPPLY-VOLTAGE SUPERVISORS

SLVS028H – APRIL 1983 – REVISED MAY 2003

- Power-On Reset Generator
- Automatic Reset Generation After Voltage Drop
- Wide Supply-Voltage Range
- Precision Voltage Sensor
- Temperature-Compensated Voltage Reference
- True and Complement Reset Outputs
- Externally Adjustable Pulse Duration

TL7702A, TL7709A, TL7712A, TL7715A . . . D OR P PACKAGE
TL7705A . . . D, P, OR PS PACKAGE,
(TOP VIEW)



description/ordering information

ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP (P)	Tube of 50	TL7702ACP	TL7702ACP
	SOIC (D)	Tube of 75	TL7702ACD	7702AC
		Reel of 2500	TL7702ACDR	
	PDIP (P)	Tube of 50	TL7705ACP	TL7705ACP
	SOIC (D)	Tube of 75	TL7705ACD	7705AC
		Reel of 2500	TL7705ACDR	
	SOP (PS)	Reel of 2000	TL7705ACPSR	T7705A
	PDIP (P)	Tube of 50	TL7709ACP	TL7709ACP
	SOIC (D)	Tube of 75	TL7709ACD	7709AC
		Reel of 2500	TL7709ACDR	
	PDIP (P)	Tube of 50	TL7712ACP	TL7709ACP
	SOIC (D)	Tube of 75	TL7712ACD	7712AC
Reel of 2500		TL7712ACDR		
PDIP (P)	Tube of 50	TL7715ACP	TL7715ACP	
SOIC (D)	Tube of 75	TL7715ACD	7715AC	
-40°C to 85°C	PDIP (P)	Tube of 50	TL7702AIP	TL7702AIP
	SOIC (D)	Tube of 75	TL7702AID	7702AI
		Reel of 2500	TL7702AIDR	
	PDIP (P)	Tube of 50	TL7705AIP	TL7705AIP
SOIC (D)	Tube of 75	TL7705AID	7705AI	
	Reel of 2500	TL7705AIDR		

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

TL7702A, TL7705A, TL7709A, TL7712A, TL7715A SUPPLY-VOLTAGE SUPERVISORS

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recommended operating conditions

		MIN	MAX	UNIT	
V _{CC}	Supply voltage	3.5	18	V	
V _{IH}	High-level input voltage at $\overline{\text{RESIN}}$	2		V	
V _{IL}	Low-level input voltage at $\overline{\text{RESIN}}$		0.6	V	
V _I	Input voltage, SENSE	TL7702A	0	See Note 2	V
		TL7705A	0	10	
		TL7709A	0	15	
		TL7712A	0	20	
		TL7715A	0	20	
I _{OH}	High-level output current, $\overline{\text{RESET}}$		-16	mA	
I _{OL}	Low-level output current, $\overline{\text{RESET}}$		16	mA	
T _A	Operating free-air temperature range	TL77xxAC	0	70	°C
		TL77xxAI	-40	85	

NOTE 2: For proper operation of the TL7702A, the voltage applied to the SENSE terminal should not exceed V_{CC} - 1 V or 6 V, whichever is less.

electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITION†	TL77xxAC TL77xxAI			UNIT	
			MIN	TYP	MAX		
V _{OH}	High-level output voltage, $\overline{\text{RESET}}$	I _{OH} = -16 mA	V _{CC} -1.5			V	
V _{OL}	Low-level output voltage, $\overline{\text{RESET}}$	I _{OL} = 16 mA	0.4			V	
V _{ref}	Reference voltage	T _A = 25°C	2.48	2.53	2.58	V	
V _{IT-}	Negative-going input threshold voltage, SENSE	T _A = 25°C	TL7702A	2.48	2.53	2.58	V
			TL7705A	4.5	4.55	4.6	
			TL7709A	7.5	7.6	7.7	
			TL7712A	10.6	10.8	11	
			TL7715A	13.2	13.5	13.8	
V _{hys}	Hysteresis, SENSE (V _{IT+} - V _{IT-})	T _A = 25°C	TL7702A	10		mV	
			TL7705A	15			
			TL7709A	20			
			TL7712A	35			
			TL7715A	45			
I _I	$\overline{\text{RESIN}}$	V _I = 2.4 V to V _{CC}	20			µA	
		V _I = 0.4 V	-100				
	SENSE	TL7702A	V _{ref} < V _I < V _{CC} - 1.5 V	0.5	2		
I _{OH}	High-level output current, $\overline{\text{RESET}}$	V _O = 18 V	50			µA	
I _{OL}	Low-level output current, $\overline{\text{RESET}}$	V _O = 0	-50			µA	
I _{CC}	Supply current	All inputs and outputs open	1.8	3		mA	

† All electrical characteristics are measured with 0.1-µF capacitors connected at REF, CT, and V_{CC} to GND.

TL7702A, TL7705A, TL7709A, TL7712A, TL7715A SUPPLY-VOLTAGE SUPERVISORS

SLVS028H – APRIL 1983 – REVISED MAY 2003

switching characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER	TEST CONDITION [†]	TL77xxAC TL77xxAI			UNIT
		MIN	TYP	MAX	
Output pulse duration	$C_T = 0.1 \mu\text{F}$	0.65	1.2	2.6	msec
Input pulse duration at $\overline{\text{RESIN}}$		0.4			μs
$t_w(\text{S})$ Pulse duration at SENSE input to switch outputs	$V_{\text{IH}} = V_{\text{IT-}} + 200 \text{ mV}, \quad V_{\text{IL}} = V_{\text{IT-}} - 200 \text{ mV}$	2			μs
t_{pd} Propagation delay time, $\overline{\text{RESIN}}$ to $\overline{\text{RESET}}$	$V_{\text{CC}} = 5 \text{ V}$	1			μs
t_r Rise time	$\overline{\text{RESET}}$	$V_{\text{CC}} = 5 \text{ V},$	See Note 5	0.2	μs
	$\overline{\text{RESET}}$			3.5	
t_f Fall time	$\overline{\text{RESET}}$	$V_{\text{CC}} = 5 \text{ V},$	See Note 5	3.5	μs
	$\overline{\text{RESET}}$			0.2	

[†] All switching characteristics are measured with 0.1- μF capacitors connected at REF and V_{CC} to GND.

NOTE 5: The rise and fall times are measured with a 4.7-k Ω load resistor at $\overline{\text{RESET}}$ and $\overline{\text{RESET}}$.

PARAMETER MEASUREMENT INFORMATION

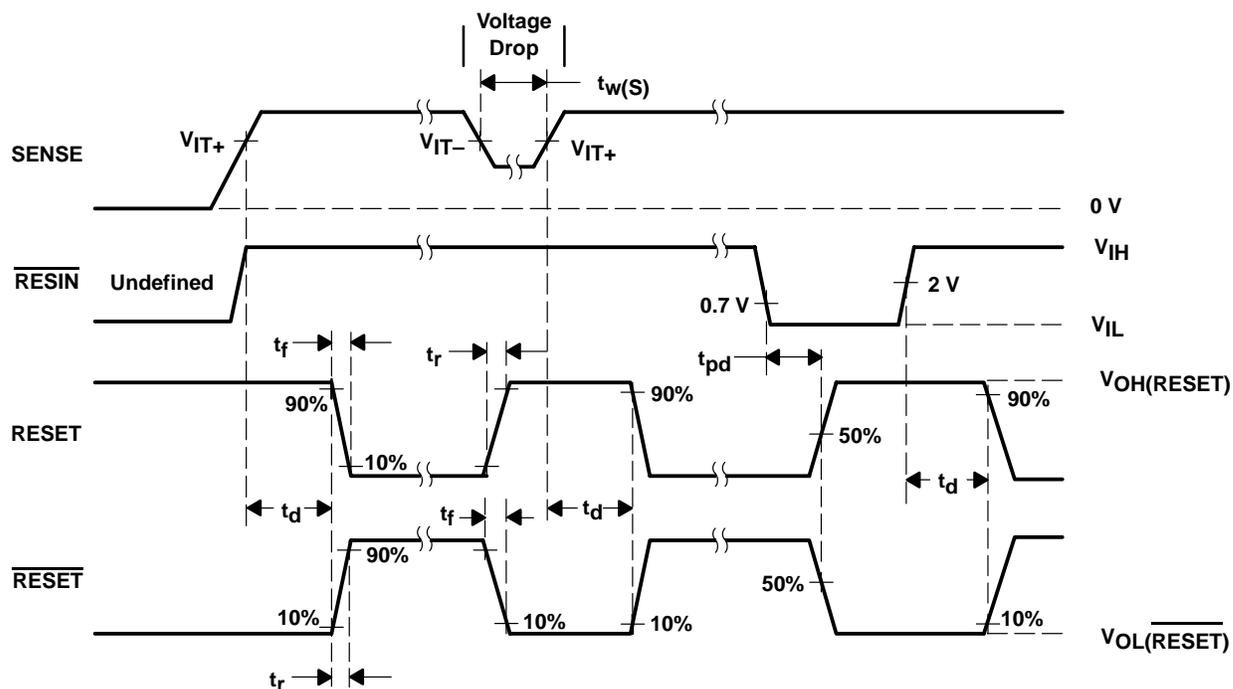


Figure 1. Voltage Waveforms

TL7702A, TL7705A, TL7709A, TL7712A, TL7715A SUPPLY-VOLTAGE SUPERVISORS

SLVS028H – APRIL 1983 – REVISED MAY 2003

TYPICAL CHARACTERISTICS†

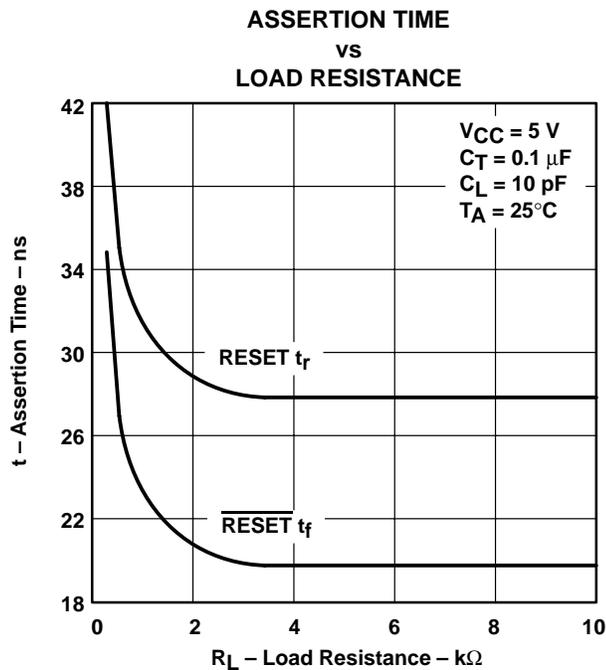


Figure 2

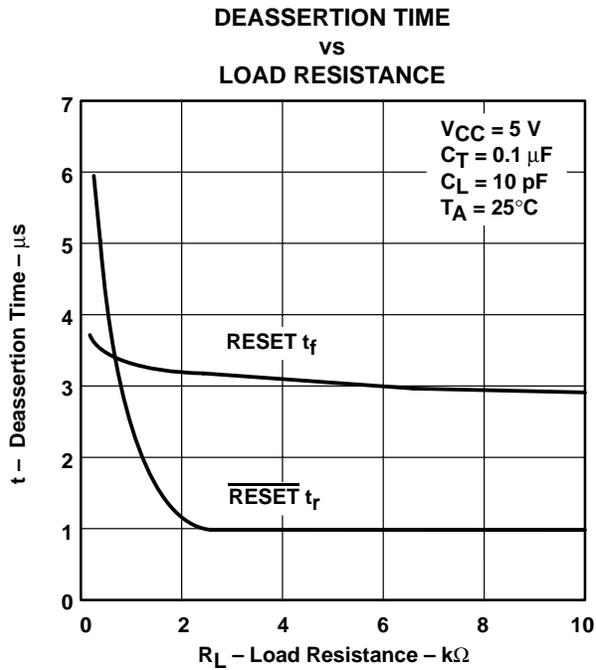


Figure 3

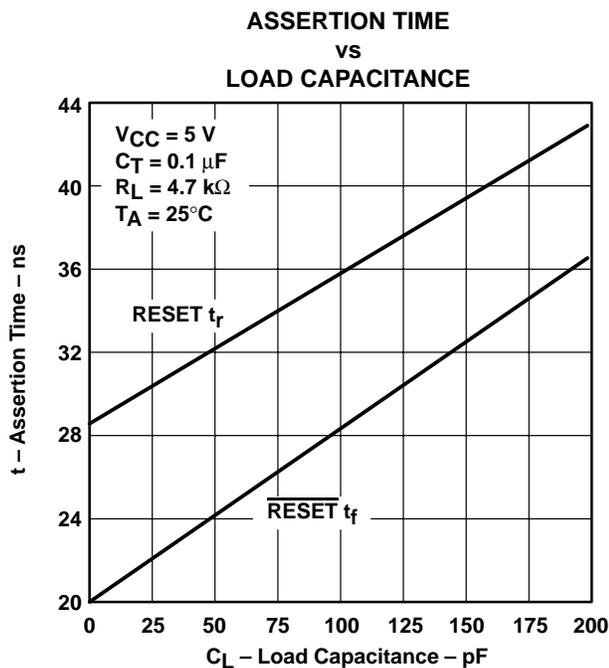


Figure 4

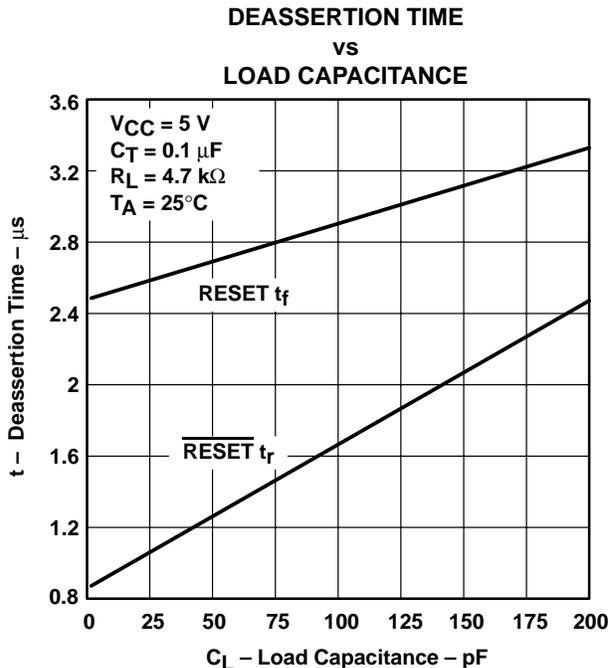


Figure 5

† For proper operation, both RESET and $\overline{\text{RESET}}$ should be terminated with resistors of similar value. Failure to do so may cause unwanted plateauing in either output waveform during switching.

TL7702A, TL7705A, TL7709A, TL7712A, TL7715A SUPPLY-VOLTAGE SUPERVISORS

SLVS028H – APRIL 1983 – REVISED MAY 2003

APPLICATION INFORMATION

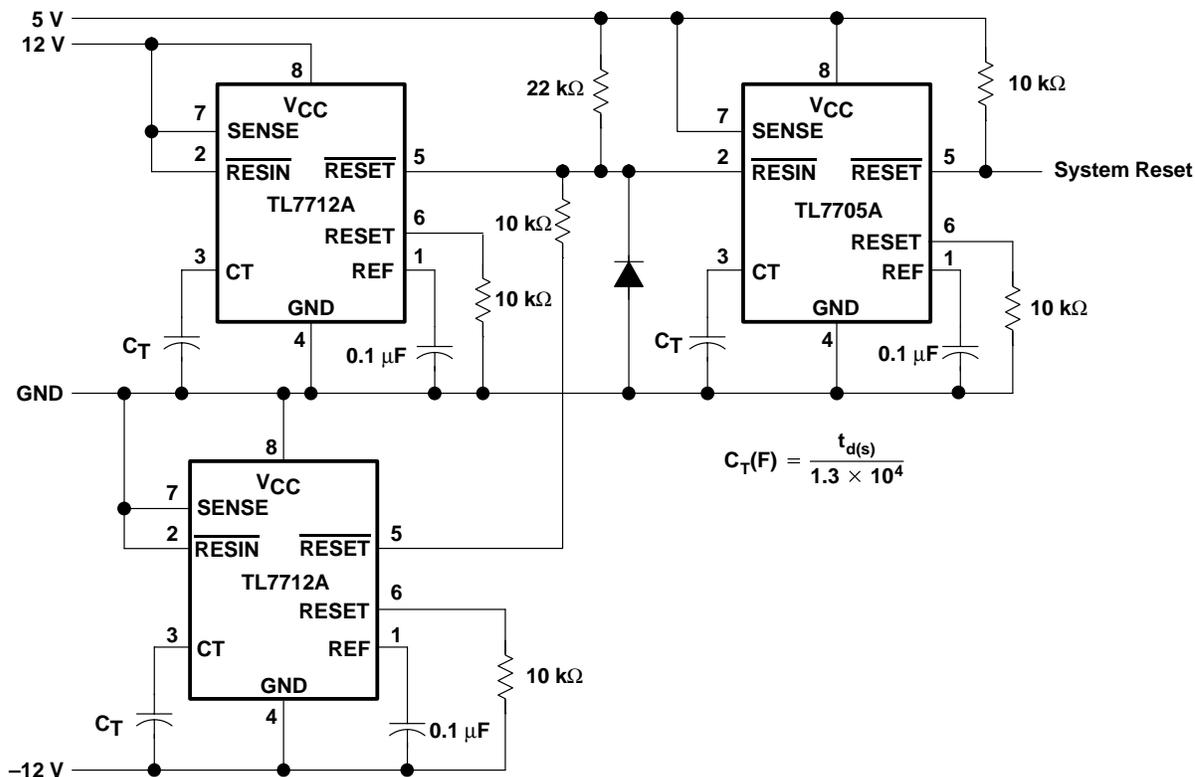


Figure 6. Multiple Power-Supply System Reset Generation

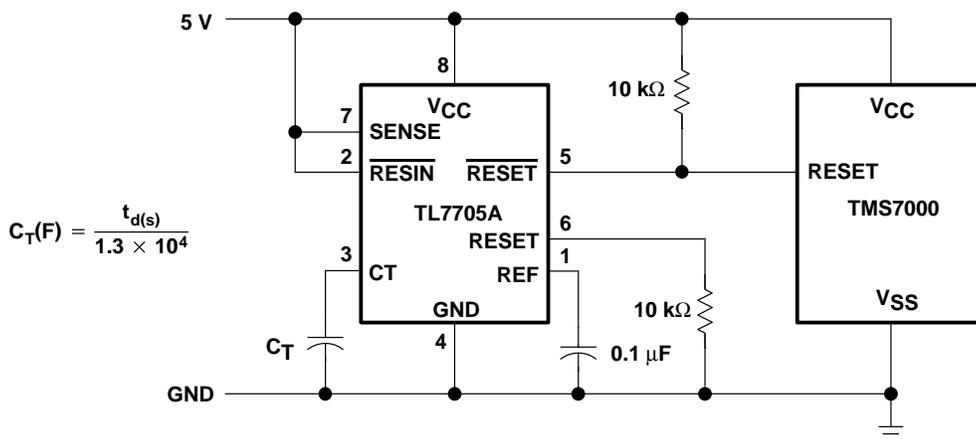


Figure 7. Reset Controller for TMS7000 System

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-88685012A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
TL7702ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702ACP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7702ACPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7702AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702AIDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702AIDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702AIP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7702AIPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7702AMFKB	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
TL7702AMJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL7702AMJGB	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL7705ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705ACP	ACTIVE	PDIP	P	8	50	Pb-Free	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						(RoHS)		
TL7705ACPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7705ACPSLE	OBSOLETE	SO	PS	8		TBD	Call TI	Call TI
TL7705ACPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705ACPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705AIDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705AIDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705AIP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7705AIPe4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7705AMFKB	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
TL7705AMJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL7705AMJGB	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL7709ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7709ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7709ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7709ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7709ACP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7709ACPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7709AID	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI
TL7709AIP	OBSOLETE	PDIP	P	8		TBD	Call TI	Call TI
TL7712ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7712ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7712ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7712ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7712ACP	ACTIVE	PDIP	P	8	50	Pb-Free	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						(RoHS)		
TL7712ACPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7712AID	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI
TL7712AIP	OBSOLETE	PDIP	P	8		TBD	Call TI	Call TI
TL7715ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7715ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7715ACP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7715ACPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7715AID	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI
TL7715AIP	OBSOLETE	PDIP	P	8		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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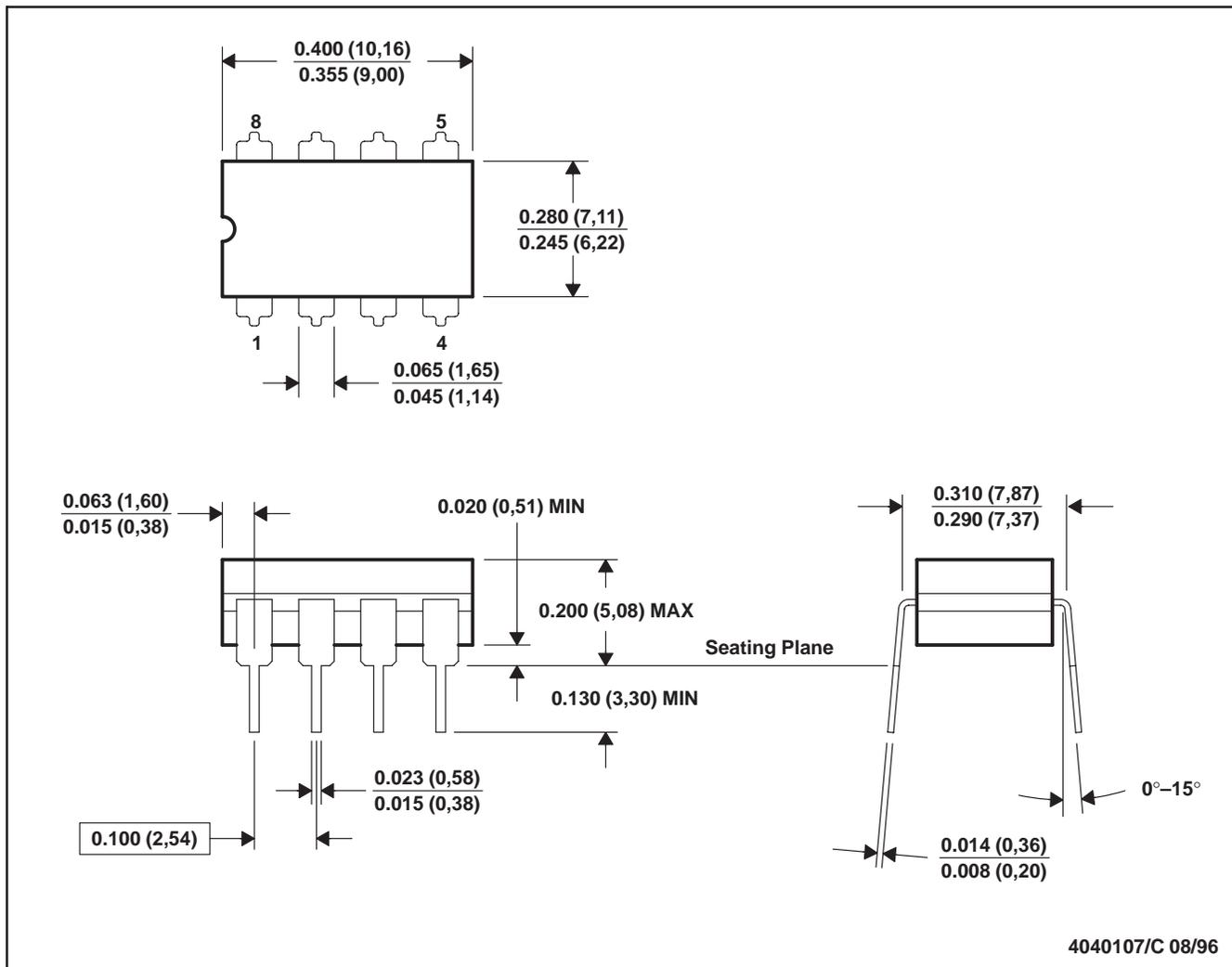
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MECHANICAL DATA

MCER001A – JANUARY 1995 – REVISED JANUARY 1997

JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification.
 - Falls within MIL STD 1835 GDIP1-T8

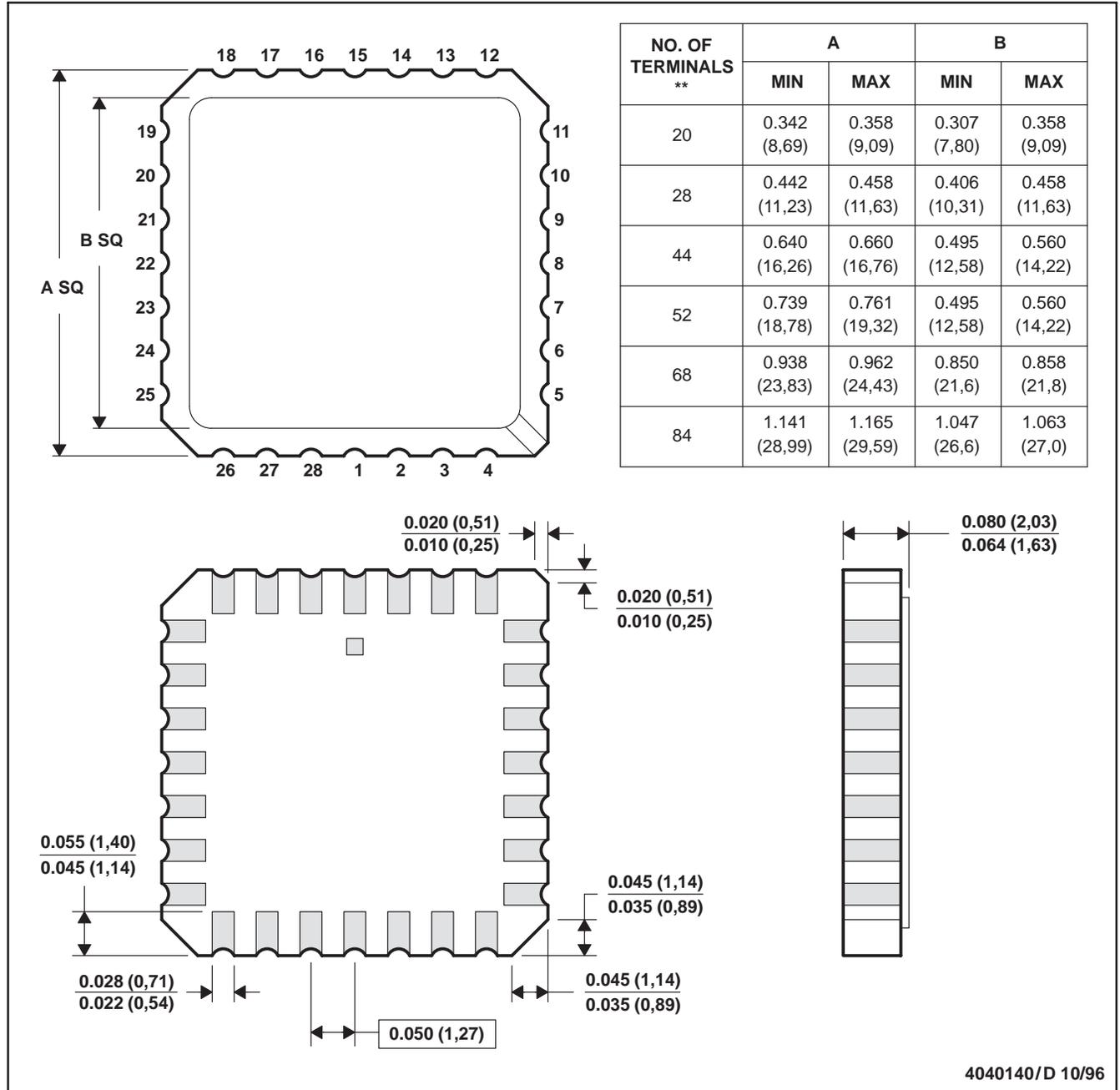
MECHANICAL DATA

MLCC006B – OCTOBER 1996

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



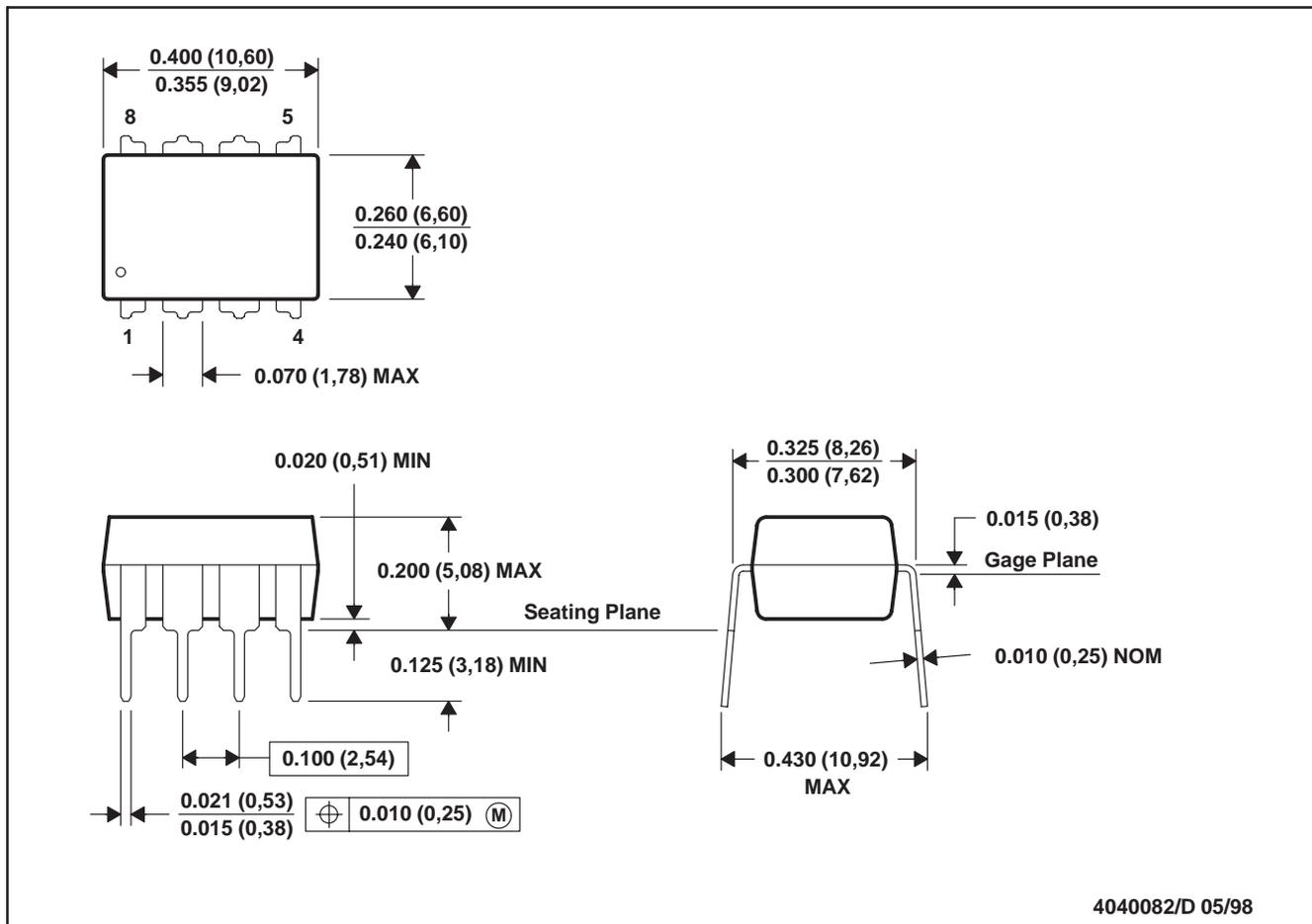
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

MECHANICAL DATA

MPDI001A – JANUARY 1995 – REVISED JUNE 1999

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE

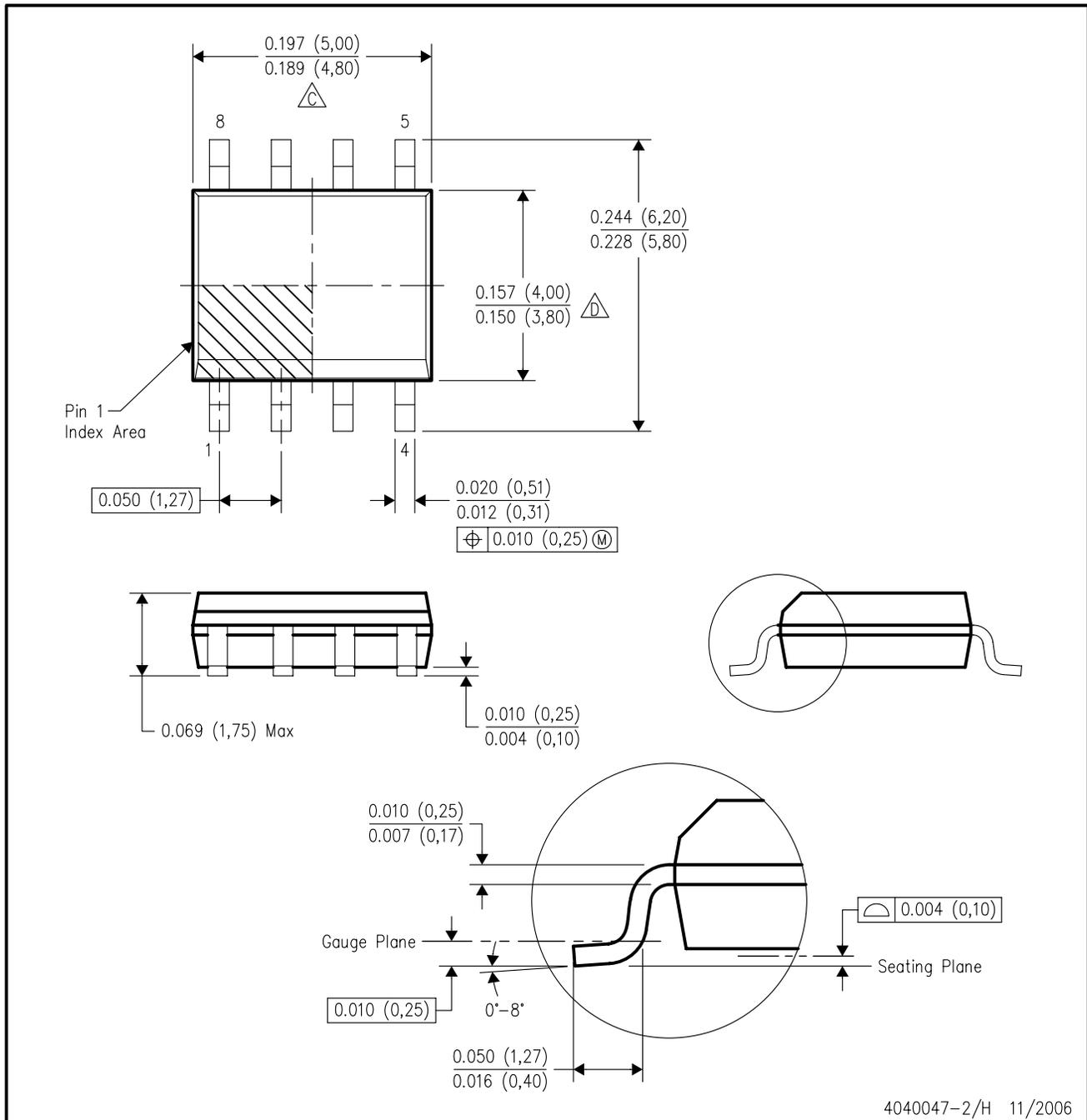


- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-001

MECHANICAL DATA

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



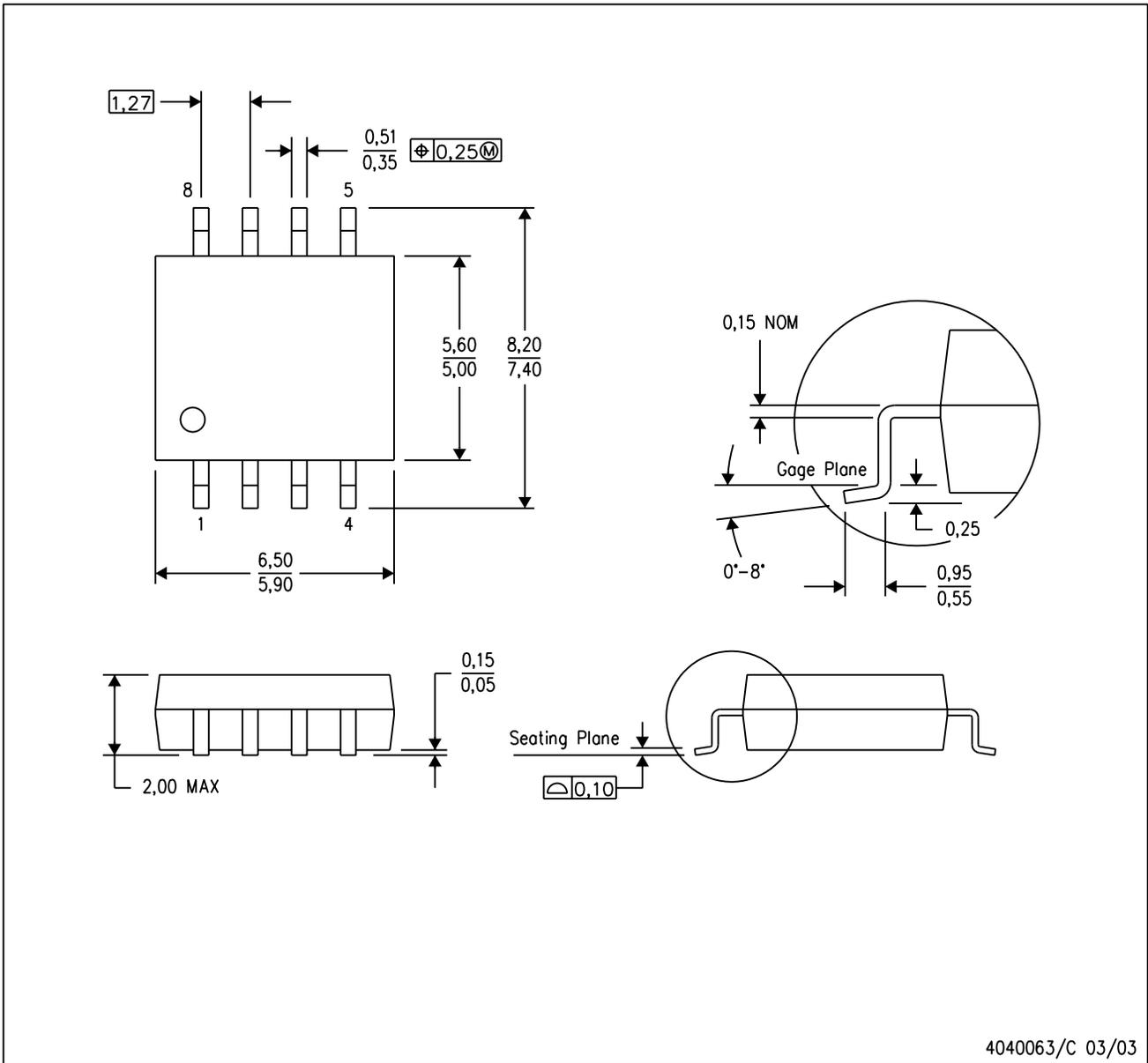
4040047-2/H 11/2006

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AA.

MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265